

Primary Characteristics

I_F	2.0	A
V_{RRM}	20~100	V
I_{FSM}	50.0	A
V_F	0.50~0.85	V

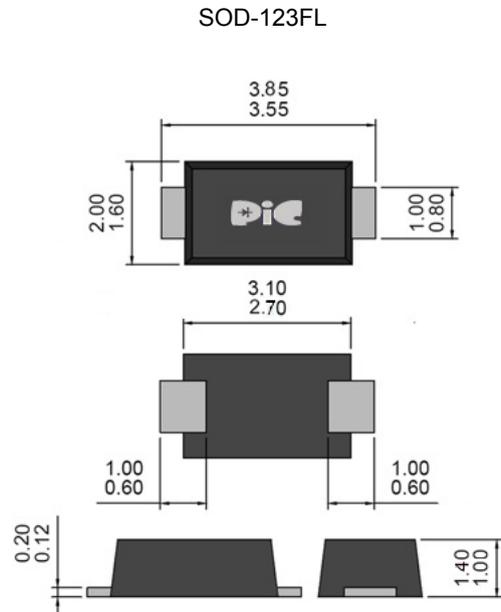
Features

- Fast switching speed
- Surface mount package suited for automatic insertion
- Low power loss, high efficiency
- Lead-free & halogen-free parts, RoHS compliant

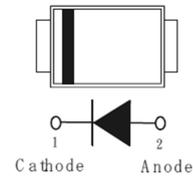
Mechanical Data

- Epoxy: UL94V-0 rated flame retardant
- Case: Molded Plastic
- Terminals: Solder plated solderable per MIL-STD-750 Method 2026
- Mounting position: Any
- Polarity: Color band denotes cathode end

Package Outline Dimensions



Unit : millimeters



Maximum Ratings (TA=25°C unless otherwise noted)

	Symbol	SS2020FL	SS2040FL	SS2060FL	SS20100FL	UNITS
Reverse Voltage	V_R	20	40	60	100	Volts
Peak Reverse Voltage	V_{RRM}	20	40	60	100	Volts
Average Rectified Current at $T_A=75^\circ\text{C}$	$I_{F(AV)}$	2.0				Amps
Non-Repetitive Peak Forward Surge Current at $t=8.3\text{ms}$	I_{FSM}	50.0				Amps
Max. Forward Voltage at 2.0A	V_F	0.50		0.70	0.85	Volts
Reverse Leakage Current at V_{RRM}	I_R	100		40		μA
Typical Thermal Resistance, Junction to Ambient(Note 1)	$R_{\theta JA}$	60				$^\circ\text{C/W}$
Operating Junction and Storage Temperature Range	T_J, T_{STG}	-55~+125				$^\circ\text{C}$

Notes:

- (1) Mounted with minimum recommended pad size, PC Board FR4.
- (2) $T_A=25^\circ\text{C}$ unless otherwise specified.

Rating and Characteristics Curves

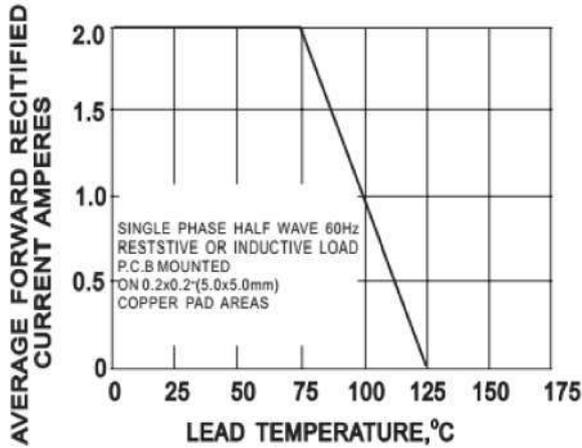


Fig. 1 Forward Current Derating Curve

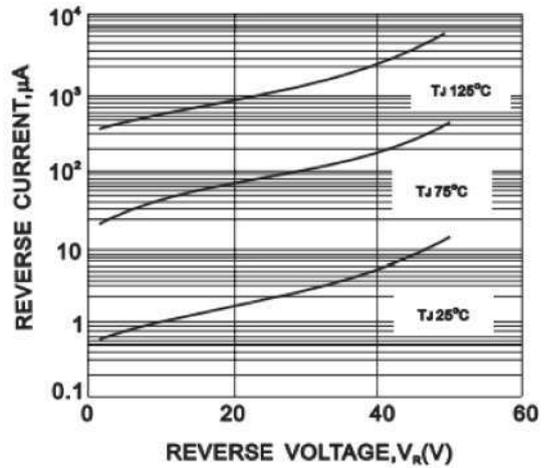


Fig. 2 Typical Junction Capacitance

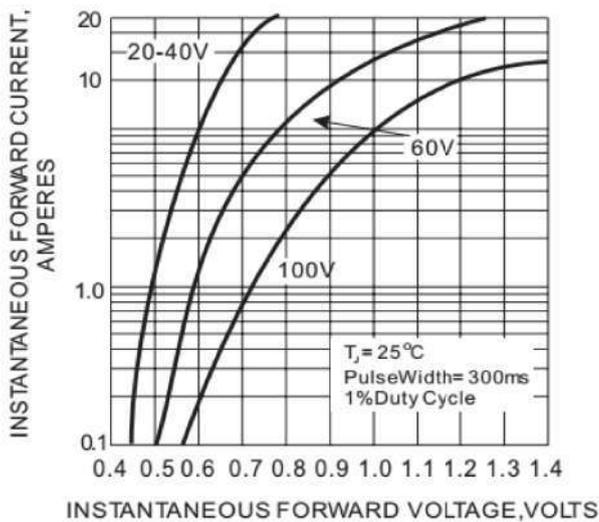
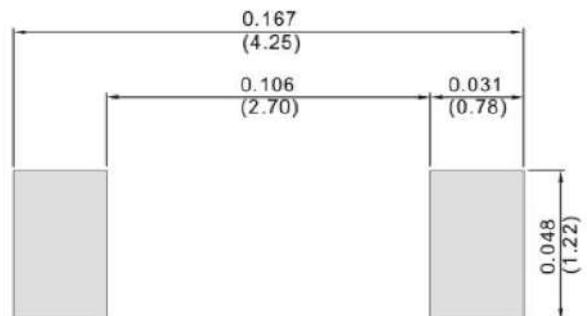


Fig. 3 Typical Reverse Characteristics

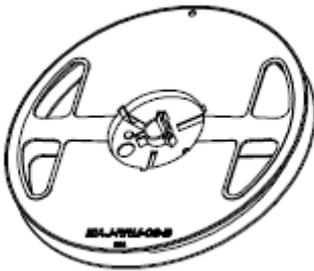
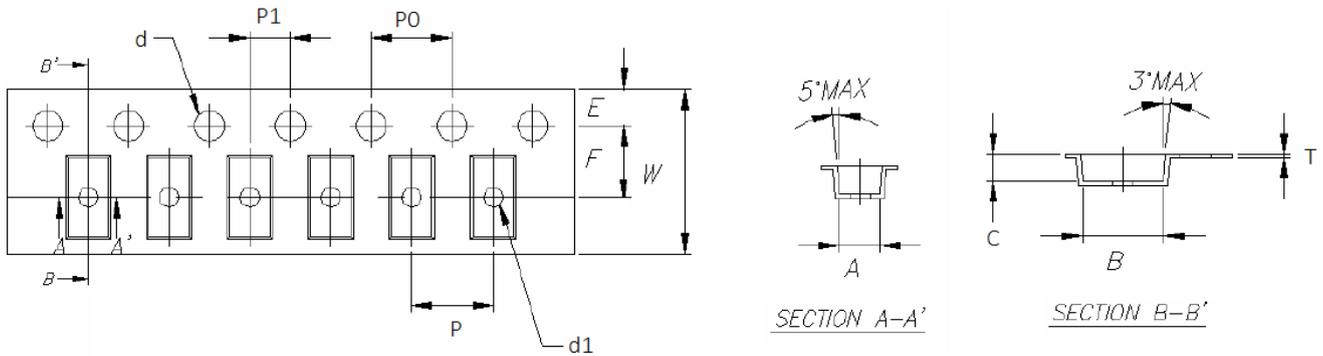
Pad Layout



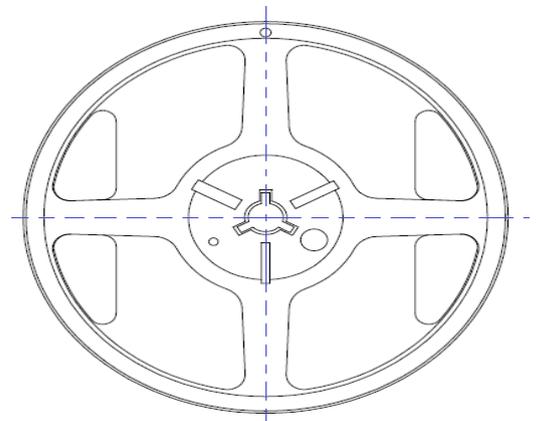
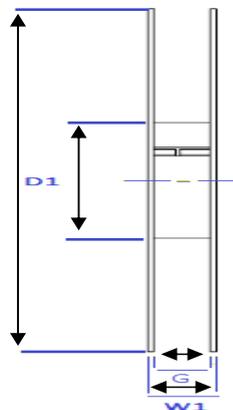
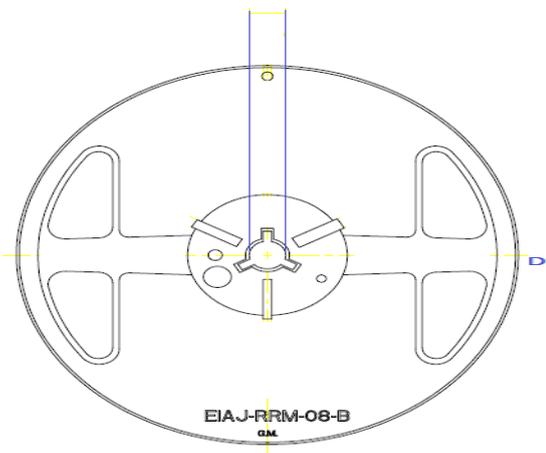
Unit: mm

Packaging Specifications

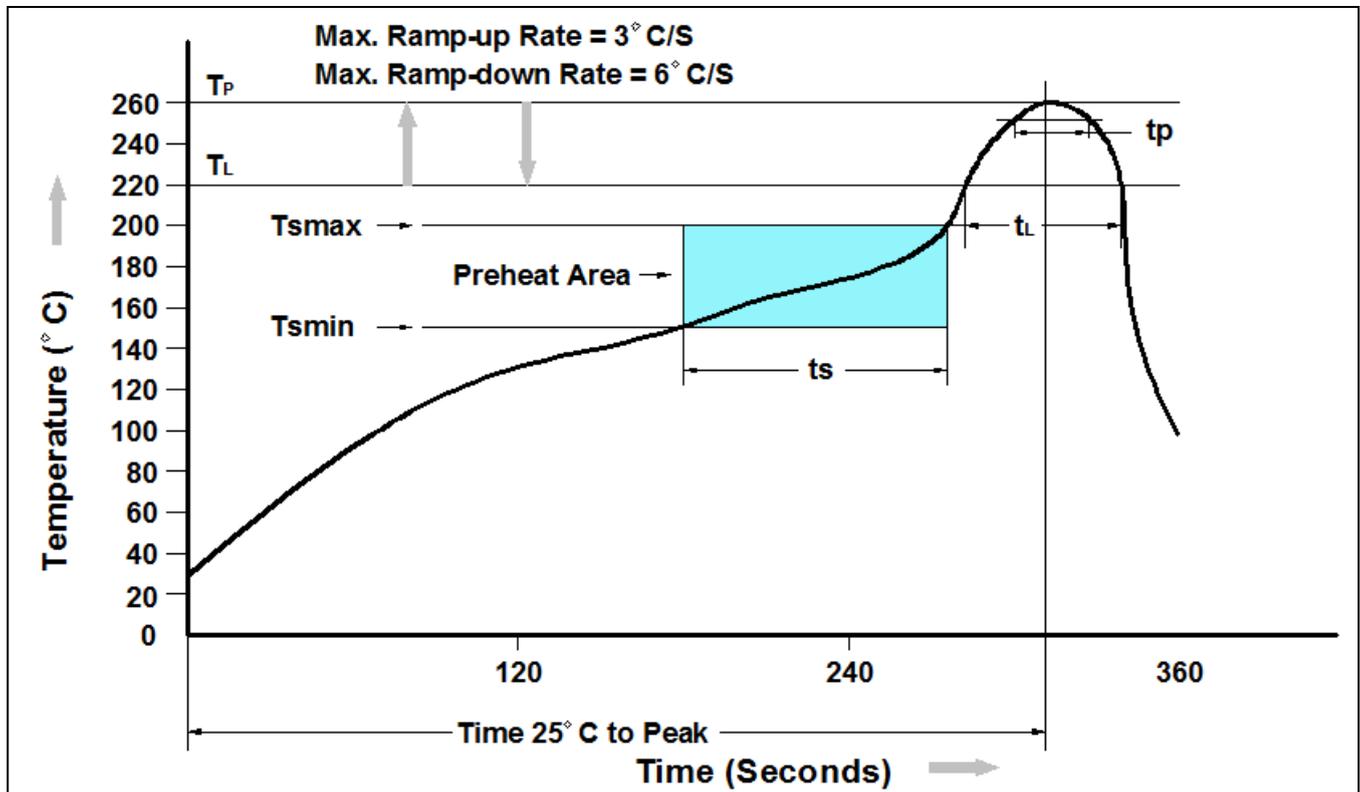
Package	W (mm)	A (mm)	B (mm)	C (mm)	d1 (mm)	d (mm)	E (mm)	F (mm)	P (mm)	P0 (mm)	P1 (mm)	T (mm)
SOD-123FL	8±0.2	2.00±0.1	3.85±0.1	1.1±0.1	1.0	1.50±0.1	1.75±0.1	3.5±0.05	4±0.1	4±0.05	2±0.05	0.23±0.05
SOD-123HE	8±0.3	2.00±0.1	4.00±0.1	1.45±0.1	1.0	1.55±0.1	1.75±0.1	3.5±0.05	4±0.1	4±0.10	2±0.05	0.23±0.10
SOD-323FL	8±0.2	1.37±0.1	2.75±0.1	0.85±0.1	1.00	1.60±0.1	1.75±0.1	3.50±0.05	4±0.1	4±0.10	-	0.20±0.10
SOD-323HE	8±0.3	1.60±0.1	2.80±0.1	0.95±0.1	1.0	1.50±0.1	1.75±0.1	3.5±0.05	4±0.1	4±0.10	2±0.05	0.23±0.10
SMAF	12±0.3	2.9±0.1	5.5±0.1	2.1±0.1	1.5	1.55±0.1	1.75±0.1	5.5±0.05	4±0.1	4±0.10	2±0.05	0.23±0.10
SMA-S	12±0.2	2.65±0.1	5.25±0.1	1.35±0.1	1.0	1.55±0.1	1.75±0.1	5.5±0.05	4±0.1	4±0.05	2±0.05	0.23±0.10
SMA-HE	12±0.2	2.65±0.1	5.25±0.1	1.35±0.1	1.0	1.55±0.1	1.75±0.1	5.5±0.05	4±0.1	4±0.05	2±0.05	0.23±0.10



Package	D (max.) (mm)	D1 (min.) (mm)	D2 (mm)	G (min.) (mm)	W1 (min.) (mm)
SOD-123FL	178	50.0	13.0±0.2	8.4	11.4
SOD-123HE	178	50.0	13.0±0.2	8.4	11.4
SOD-323FL	178	50.2	13.0±0.2	8.0	11.5
SOD-323HE	178	50.0	13.0±0.2	8.4	11.4
SMAF	178	50.0	13.0±0.2	12.4	18.0
	330	50.0	13.0±0.2	12.4	18.0
SMA-S	178	50.0	13.0±0.2	12.4	18.0
SMA-HE	178	50.0	13.0±0.2	12.4	18.0



Recommend IR Reflow Soldering Thermal Profile



Profile Feature	Pb-Free Assembly Profile
Temperature Min. (T _{smin})	150°C
Temperature Max. (T _{smax})	200°C
Time (t _s) from (T _{smin} to T _{smax})	60-120 seconds
Average Ramp-up Rate (t _L to t _P)	3°C/second max.
Liquidous Temperature (T _L)	217°C
Time (t _L) Maintained Above (T _L)	60 – 150 seconds
Peak Temperature	260°C +0°C / -5°C
Time (t _P) within 5°C of actual Peak Temperature	30 seconds
Ramp-down Rate (T _P to T _L)	6°C/second max
Time 25°C to Peak Temperature	8 minutes max.

Ordering Information

Part Number	Description	Quantity
SS2020FL~SS20100FL	SOD-123FL Reel	3000 pcs

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